

30V N-Channel Enhancement Mode MOSFET

Voltage 30 V Current 62 A

Features

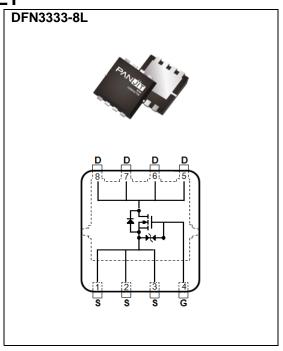
- RDS(ON), VGS@10V, ID@10A< $5.5m\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_D@6A<8.3m\Omega$
- Excellent FOM
- Logic Level Drive
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN3333-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.03 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	30	- V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C		62		
	T _C =100°C	l _D	39	Α	
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	248		
Power Dissipation	T _C =25°C		31.3	W	
	T _C =100°C	Po	12.5		
Continuous Drain Current(Note 4)	T _A =25°C	l _D	16	А	
	T _A =70°C		12.7		
Power Dissipation	T _A =25°C	,	2.1	W	
	T _A =70°C	Pb	1.3		
Single Pulse Avalanche Energy(Note 5)		Eas	28	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~150	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{θJC}	4	°C/W	
	Junction to Ambient	R _{θJA}	60		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.3	1.7	2.5		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =10A	-	4.6	5.5	mΩ	
		V _{GS} =4.5V, I _D =6A	-	6.4	8.3		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	±1	uA	
	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±10	uA	
Gate-Source Leakage Current		V _{GS} =±10V, V _{DS} =0V	-	-	±1		
Dynamic ^(Note 6)	_						
Total Gate Charge	Q_g	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	15	-	nC	
Gate-Source Charge	Qgs	V _{DS} =24V, I _D =10A, V _{GS} =10V ^(Note 2,3)	-	3.4	-		
Gate-Drain Charge	Q_{gd}	VGS=1UV(Note 2,3)	-	2.1	-		
Input Capacitance	Ciss	.,	-	923	-	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	442	-		
Reverse Transfer Capacitance	Crss	f=1MHz	-	36	-		
Gate resistance	Rg	f=1MHz	-	1.6	-	Ω	
Turn-On Delay Time	td _(on)		-	13	-	ns	
Turn-On Rise Time	tr	V _{DS} =24V, I _D =10A,	-	8	-		
Turn-Off Delay Time	td(off)	V _{GS} =10V, R _G =3Ω	-	24	-		
Turn-Off Fall Time	tf	(Note 2,3)	-	23	-		
Drain-Source Diode							
Diode Forward Current	Is	T 0500	-	-	62	A	
Pulsed Diode Forward Current	I _{SM}	T _C =25°C	-	-	248		
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.8	1.1	V	
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	27	-	ns	
Reverse Recovery Charge	Qrr	dls/dt=100A/us ^(Note 2,3)	_	13	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an ReJc=4°C/W.
- 4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. 6. The test condition is L=0.5mH, I_{AS}=11A, V_{DD}=30V, V_{GS}=10V, Starting TJ=25°C. the chip is about to carry I_{AS}≈21A.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

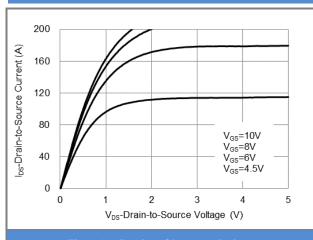


Fig.1 On-Region Characteristics

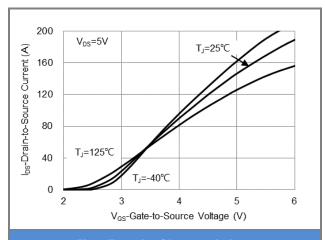


Fig.2 Transfer Characteristics

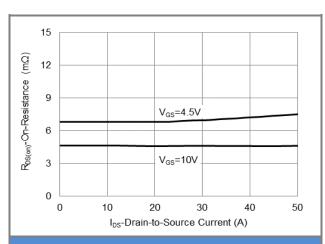


Fig.3 On-Resistance vs. Drain Current

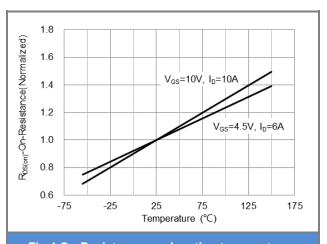
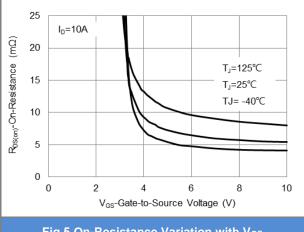
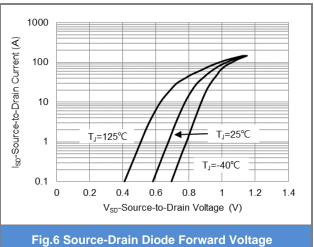


Fig.4 On-Resistance vs. Junction temperature









TYPICAL CHARACTERISTIC CURVES

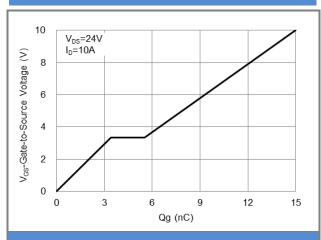


Fig.7 Gate-Charge Characteristics

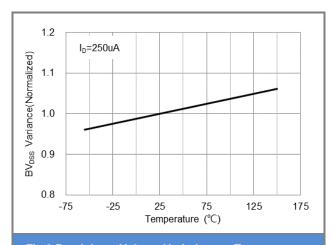


Fig.8 Breakdown Voltage Variation vs. Temperature

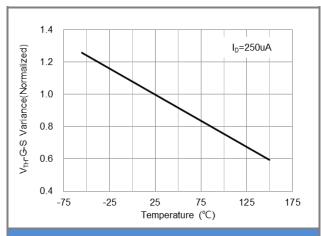


Fig.9 Threshold Voltage Variation with Temperature

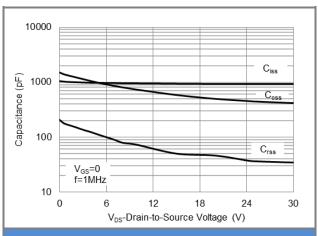
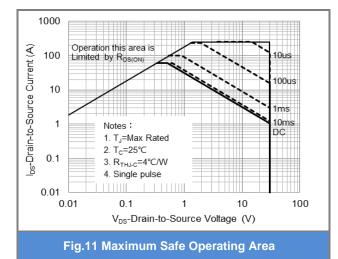
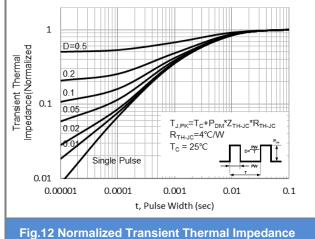


Fig.10 Capacitance vs. Drain-Source Voltage



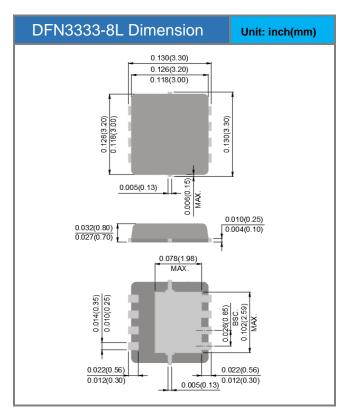


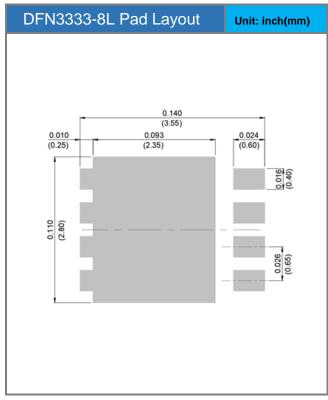


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJQ4526P	DFN3333-8L	5K pcs / 13" reel	4526	

Packaging Information & Mounting Pad Layout







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